



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Coyle, et al.

Serial No.: 09/992,387

Filed: 11/16/01

For: Flip-Chip on Film Assembly for Ball Grid Array Packages

Docket No.: TI-31794

Examiner: Lewis, Monica

Art Unit: 2822

2822
#141 Response
A7nd
6/3/03


Amendment under 37 CFR 1.111

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on

May 27, 2003.


Elizabeth Austin

Dear Sir:

The following remarks are offered in response to the Examiner's Office Action dated 02/26/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

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